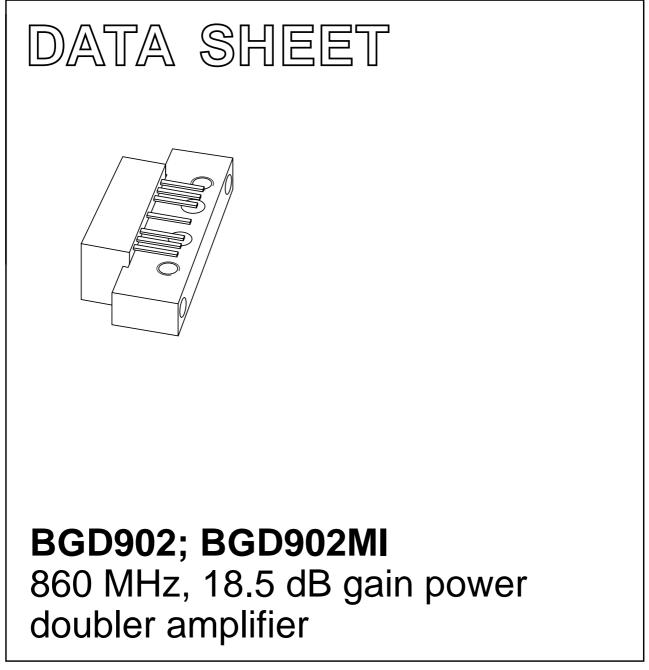
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1999 Mar 29 2001 Nov 02



FEATURES

- Excellent linearity
- Extremely low noise
- Excellent return loss properties
- Silicon nitride passivation
- Rugged construction
- Gold metallization ensures excellent reliability.

APPLICATIONS

• CATV systems operating in the 40 to 900 MHz frequency range.

DESCRIPTION

Hybrid amplifier modules in a SOT115J package operating with a voltage supply of 24 V (DC).

Both modules are electrically identical only the pinning is different.

BGD902; BGD902MI

PINNING - SOT115J

PIN	DESCRIPTION		
	BGD902	BGD902MI	
1	input	output	
2, 3	common	common	
5	+V _B	+V _B	
7, 8	common	common	
9	output	input	

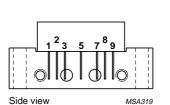


Fig.1 Simplified outline.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G _p	power gain	f = 50 MHz	18.2	18.8	dB
		f = 900 MHz	19	20	dB
I _{tot}	total current consumption (DC)	V _B = 24 V	405	435	mA

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER		MAX.	UNIT
V _B	supply voltage		30	V
Vi	RF input voltage		70	dBmV
T _{stg}	storage temperature		+100	°C
T _{mb}	operating mounting base temperature		+100	°C

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CHARACTERISTICS

Bandwidth 40 to 900 MHz; V_B = 24 V; T_mb = 35 °C; Z_S = Z_L = 75 Ω

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
G _p	power gain	f = 50 MHz	18.2	18.5	18.8	dB
		f = 900 MHz	19	19.5	20	dB
SL	slope cable equivalent	f = 40 to 900 MHz		0.9	1.4	dB
FL	flatness of frequency response	f = 40 to 900 MHz	-	±0.15	±0.3	dB
s ₁₁	input return losses	f = 40 to 80 MHz	21	24	-	dB
		f = 80 to 160 MHz	22	26	-	dB
		f = 160 to 320 MHz	22	28	-	dB
		f = 320 to 640 MHz	19	22	-	dB
		f = 640 to 900 MHz	18	21	-	dB
\$ ₂₂	output return losses	f = 40 to 80 MHz	25	32	-	dB
		f = 80 to 160 MHz	25	33	-	dB
		f = 160 to 320 MHz	21	29	-	dB
		f = 320 to 750 MHz	20	25	-	dB
		f = 750 to 900 MHz	19	22	-	dB
s ₂₁	phase response	f = 50 MHz	-45	_	+45	deg
СТВ	composite triple beat	49 chs flat; V _o = 47 dBmV; f _m = 859.25 MHz	-	-68.5	-67	dB
		77 chs flat; $V_0 = 44 \text{ dBmV}$; $f_m = 547.25 \text{ MHz}$	_	-70	-68	dB
		110 chs flat; $V_0 = 44 \text{ dBmV}$; $f_m = 745.25 \text{ MHz}$	-	-63.5	-62	dB
		129 chs flat; $V_0 = 44 \text{ dBmV}$; $f_m = 859.25 \text{ MHz}$	-	-60	-58	dB
		110 chs; $f_m = 400$ MHz; V _o = 49 dBmV at 550 MHz; note 1	-	-64	-62	dB
		129 chs; $f_m = 650$ MHz; V _o = 49.5 dBmV at 860 MHz; note 2	-	-58.5	-56.5	dB
X _{mod}	cross modulation	49 chs flat; $V_0 = 47 \text{ dBmV}$; $f_m = 55.25 \text{ MHz}$	_	-66.5	-64	dB
		77 chs flat; $V_o = 44 \text{ dBmV}$; $f_m = 55.25 \text{ MHz}$	_	-69.5	-67	dB
		110 chs flat; V _o = 44 dBmV; f _m = 55.25 MHz	_	-66	-63.5	dB
		129 chs flat; V _o = 44 dBmV; f _m = 55.25 MHz	-	-64.5	-62	dB
		110 chs; $f_m = 400$ MHz; V _o = 49 dBmV at 550 MHz; note 1	-	-63	-60	dB
		129 chs; $f_m = 860$ MHz; V _o = 49.5 dBmV at 860 MHz; note 2	-	-61	-58	dB
CSO	composite second order distortion	49 chs flat; $V_0 = 47$ dBmV; $f_m = 860.5$ MHz	-	-65	-62	dB
		77 chs flat; $V_o = 44 \text{ dBmV}$; $f_m = 548.5 \text{ MHz}$	-	-72	-67	dB
		110 chs flat; $V_0 = 44 \text{ dBmV}$; $f_m = 746.5 \text{ MHz}$	-	-65	-60	dB
		129 chs flat; $V_0 = 44 \text{ dBmV}$; $f_m = 860.5 \text{ MHz}$	-	-61	-58	dB
		110 chs; $f_m = 250$ MHz; V _o = 49 dBmV at 550 MHz; note 1	-	-67	-63	dB
		129 chs; $f_m = 250 \text{ MHz}$; V _o = 49.5 dBmV at 860 MHz; note 2	-	-62	-58	dB

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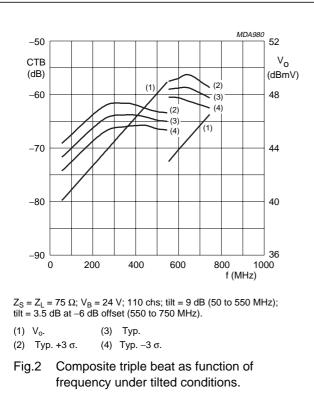
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
d ₂	second order distortion	note 3	-	-80	-74	dB
		note 4	-	-83	-77	dB
		note 5	-	-84	-78	dB
Vo	output voltage	d _{im} = -60 dB; note 6	64.5	66	-	dBmV
		d _{im} = -60 dB; note 7	65.5	67	-	dBmV
		d _{im} = -60 dB; note 8	67.5	69	-	dBmV
		CTB compression = 1 dB; 129 chs flat; f = 859.25 MHz	48.5	49.5	-	dBmV
		CSO compression = 1 dB; 129 chs flat; f = 860.5 MHz	50	53	-	dBmV
F	noise figure	f = 50 MHz	-	4.5	5	dB
		f = 550 MHz	-	5	5.5	dB
		f = 750 MHz	-	5.5	6.5	dB
		f = 900 MHz	_	6.5	8	dB
I _{tot}	total current consumption (DC)	note 9	405	420	435	mA

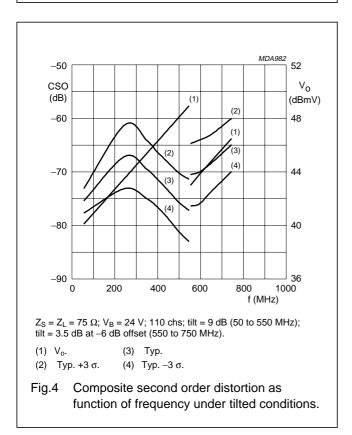
Notes

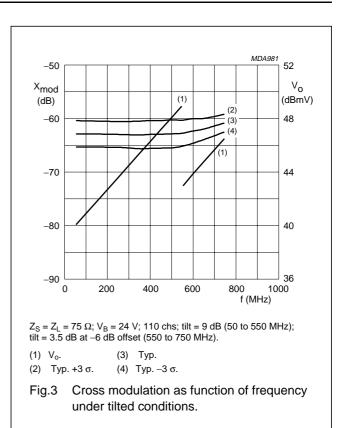
- 1. Tilt = 9 dB (50 to 550 MHz); tilt = 3.5 dB at -6 dB offset (550 to 750 MHz).
- 2. Tilt = 12.5 dB (50 to 860 MHz).
- 3. $f_p = 55.25 \text{ MHz}; V_p = 44 \text{ dBmV};$ $f_q = 805.25 \text{ MHz}; V_q = 44 \text{ dBmV};$ measured at $f_p + f_q = 860.5 \text{ MHz}.$
- 4. $f_p = 55.25 \text{ MHz}; V_p = 44 \text{ dBmV};$ $f_q = 691.25 \text{ MHz}; V_q = 44 \text{ dBmV};$ measured at $f_p + f_q = 746.5 \text{ MHz}.$
- 5. $f_p = 55.25 \text{ MHz}; V_p = 44 \text{ dBmV};$ $f_q = 493.25 \text{ MHz}; V_q = 44 \text{ dBmV};$ measured at $f_p + f_q = 548.5 \text{ MHz}.$
- 6. Measured according to DIN45004B: $f_p = 851.25 \text{ MHz}; V_p = V_o;$ $f_q = 858.25 \text{ MHz}; V_q = V_o -6 \text{ dB};$ $f_r = 860.25 \text{ MHz}; V_r = V_o -6 \text{ dB};$ measured at $f_p + f_q - f_r = 849.25 \text{ MHz}.$
- 7. Measured according to DIN45004B: $f_p = 740.25 \text{ MHz}; V_p = V_0;$ $f_q = 747.25 \text{ MHz}; V_q = V_o -6 \text{ dB};$ $f_r = 749.25 \text{ MHz}; V_r = V_o -6 \text{ dB};$ measured at $f_p + f_q - f_r = 738.25 \text{ MHz}.$
- $\frac{1}{10} = \frac{1}{10} = \frac{1}{10}$
- 8. Measured according to DIN45004B: $f_p = 540.25 \text{ MHz}; V_p = V_0;$ $f_q = 547.25 \text{ MHz}; V_q = V_0 - 6 \text{ dB};$ $f_r = 549.25 \text{ MHz}; V_r = V_0 - 6 \text{ dB};$ measured at $f_p + f_q - f_r = 538.25 \text{ MHz}.$
- 9. The module normally operates at $V_B = 24$ V, but is able to withstand supply transients up to 35 V.

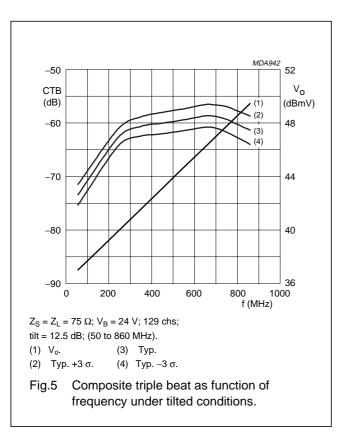
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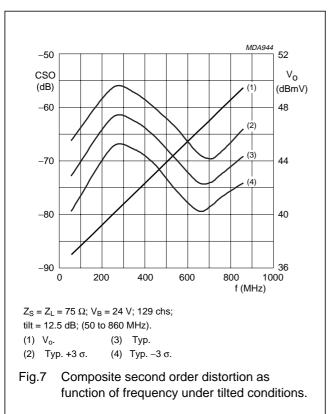
860 MHz, 18.5 dB gain power doubler amplifier



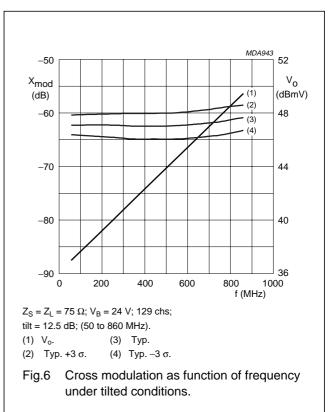




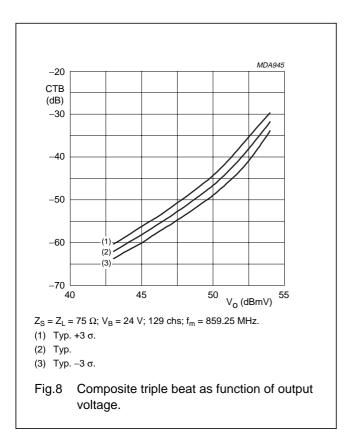


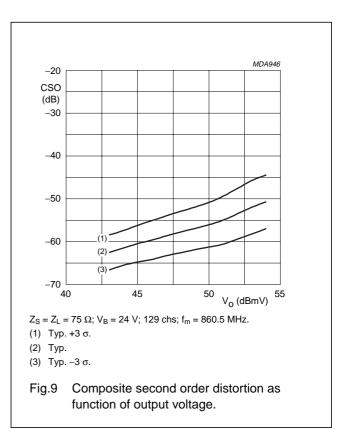


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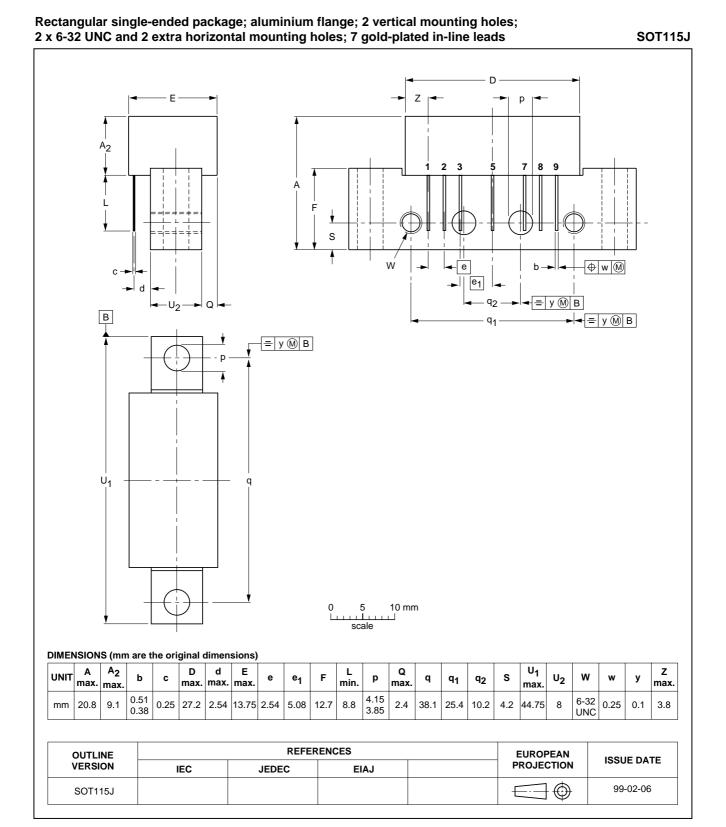
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PACKAGE OUTLINE



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DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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